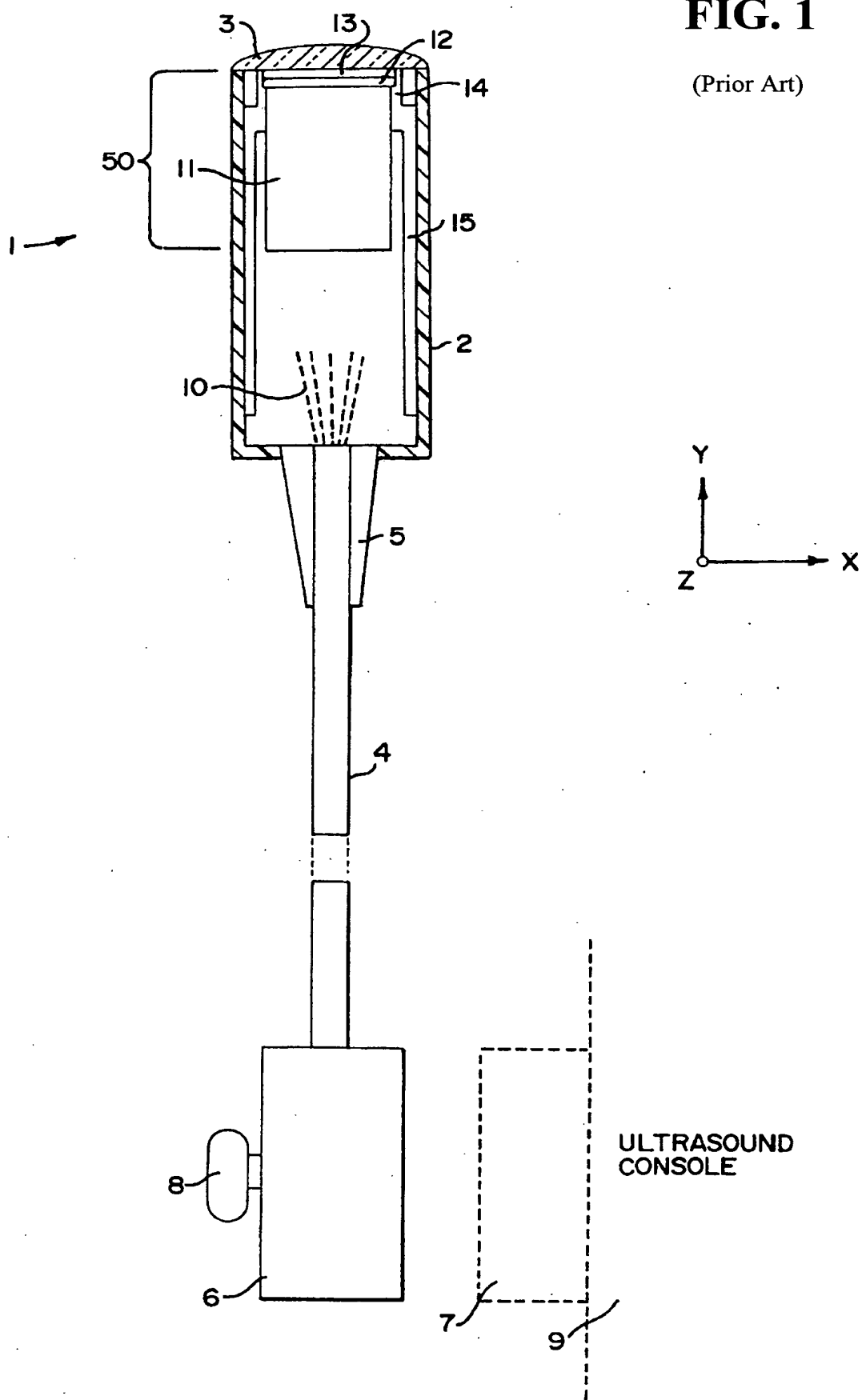
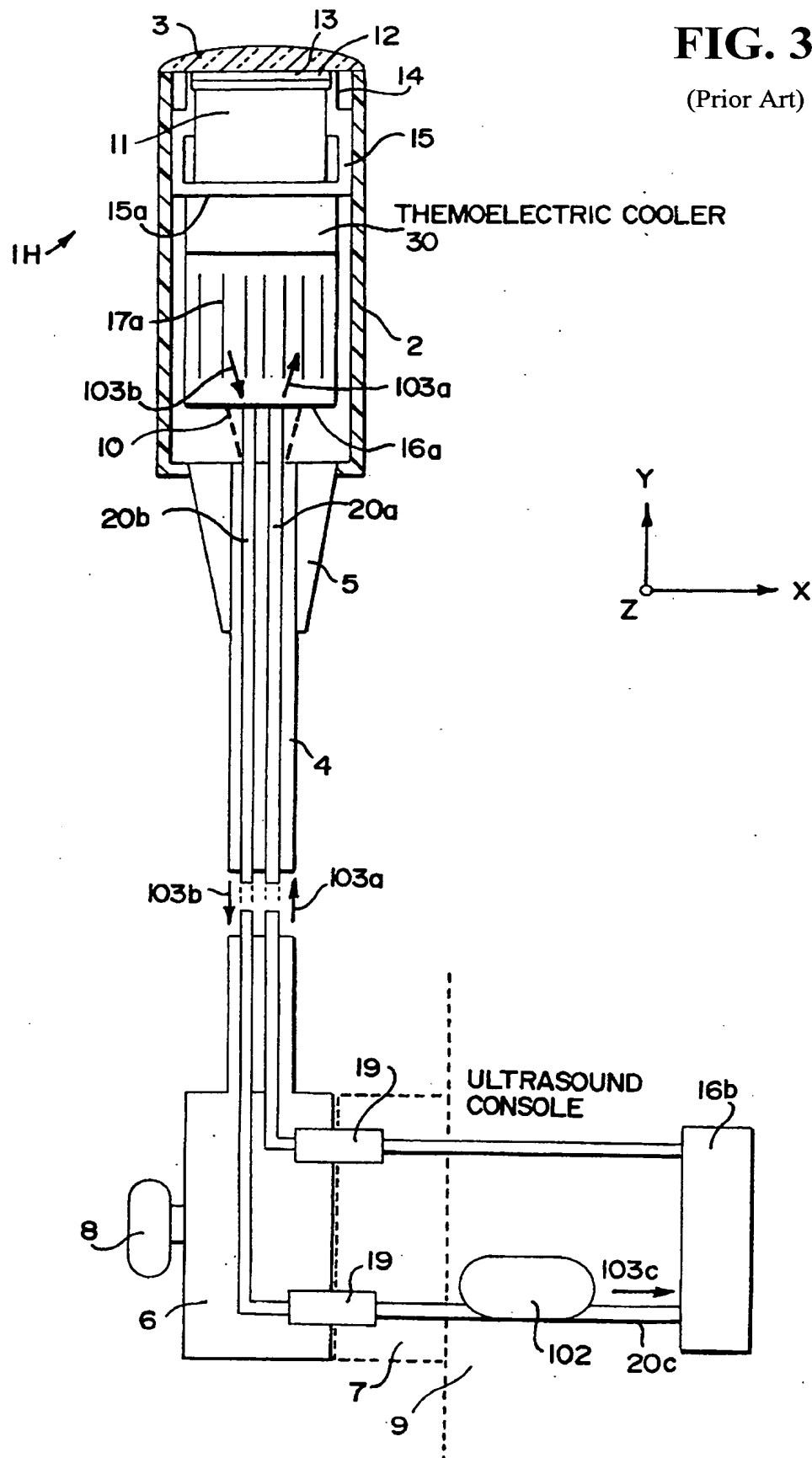


**FIG. 1** (1/11)

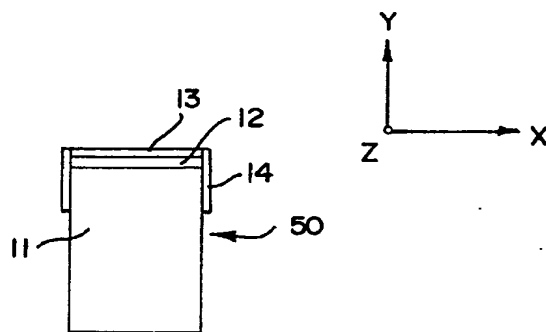
(Prior Art)





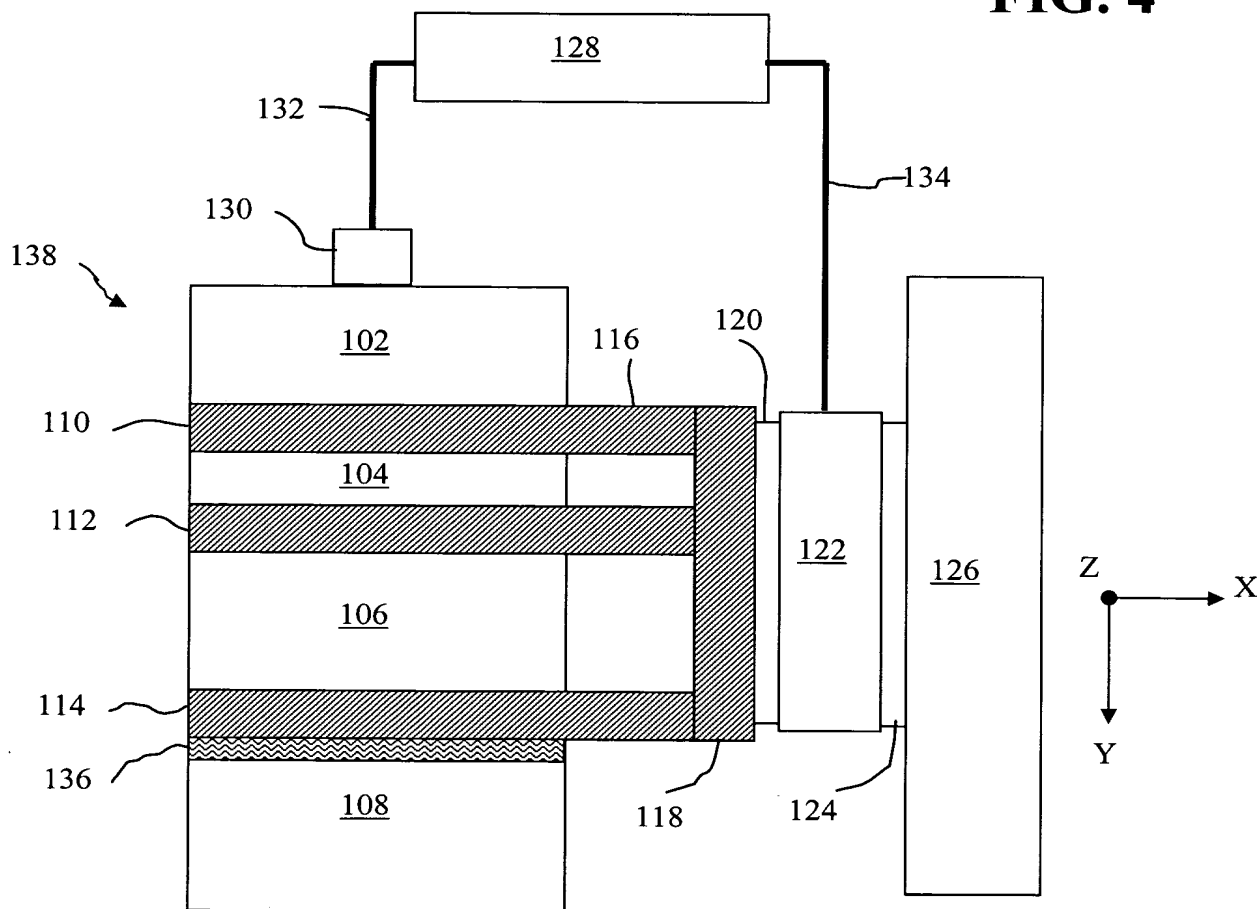
**FIG. 2**

(3/11)



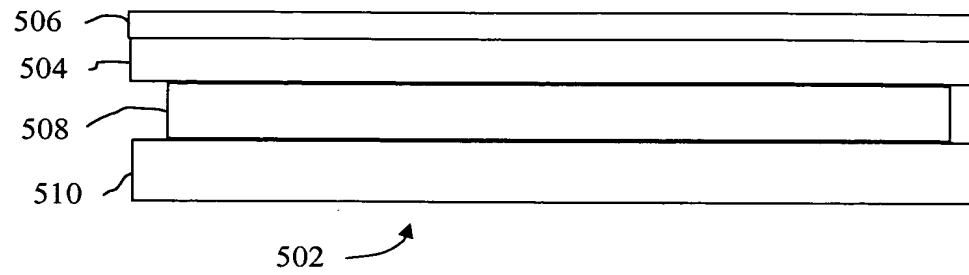
100

**FIG. 4**

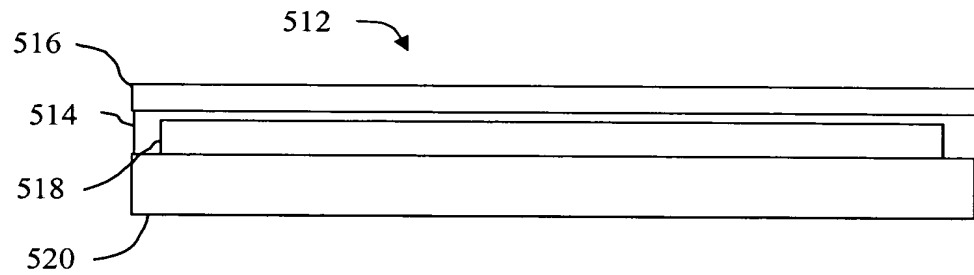


**FIG. 5A**

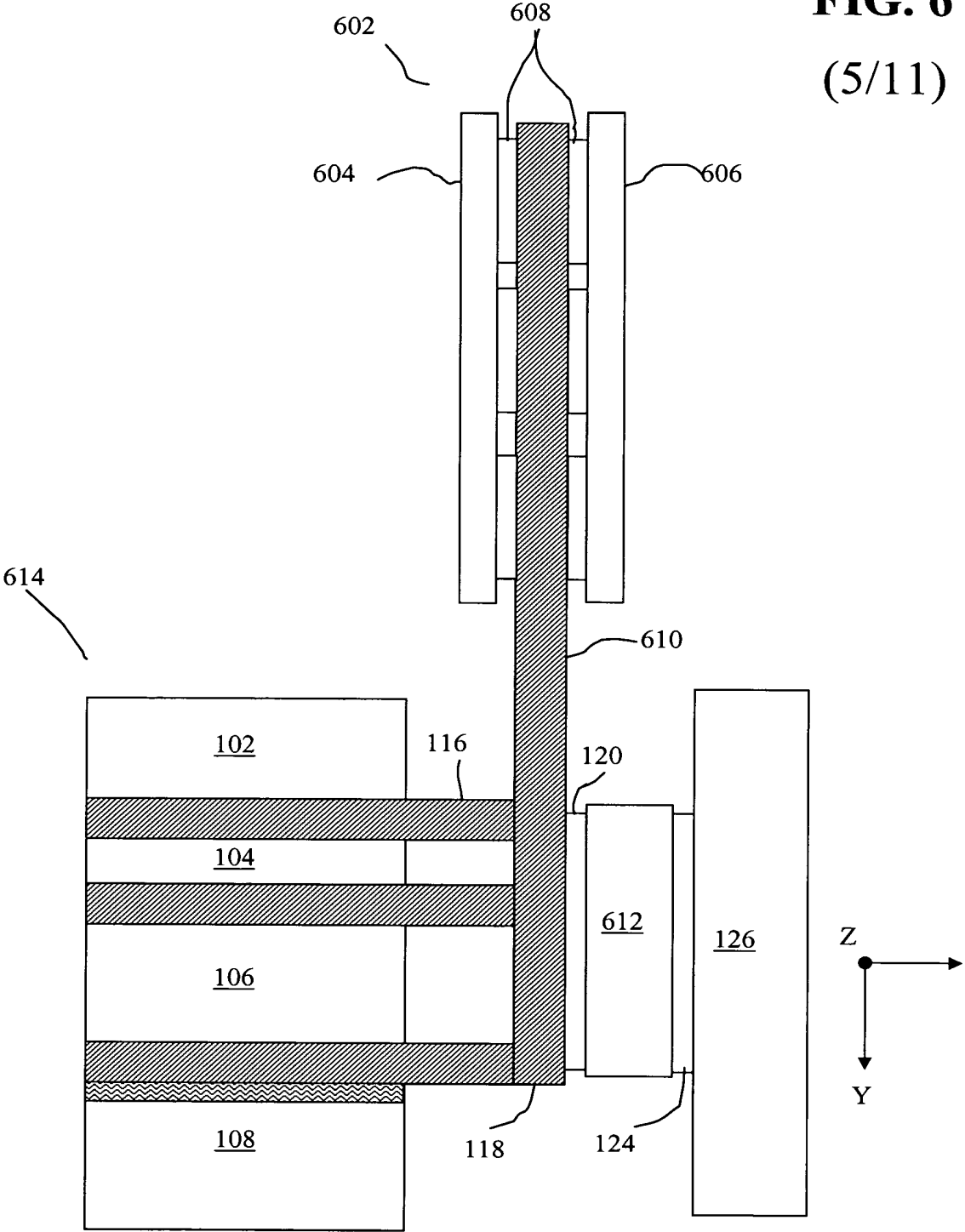
(4/11)



**FIG. 5B**



**FIG. 6**  
(5/11)



ELECTRONICS SUBASSEMBLY  
WITH HEAT GENERATING COMPONENTS

FIG. 7A

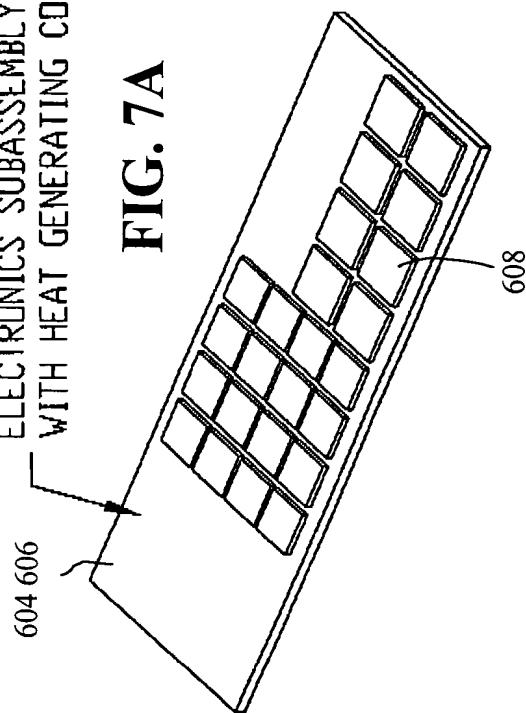


FIG. 7C

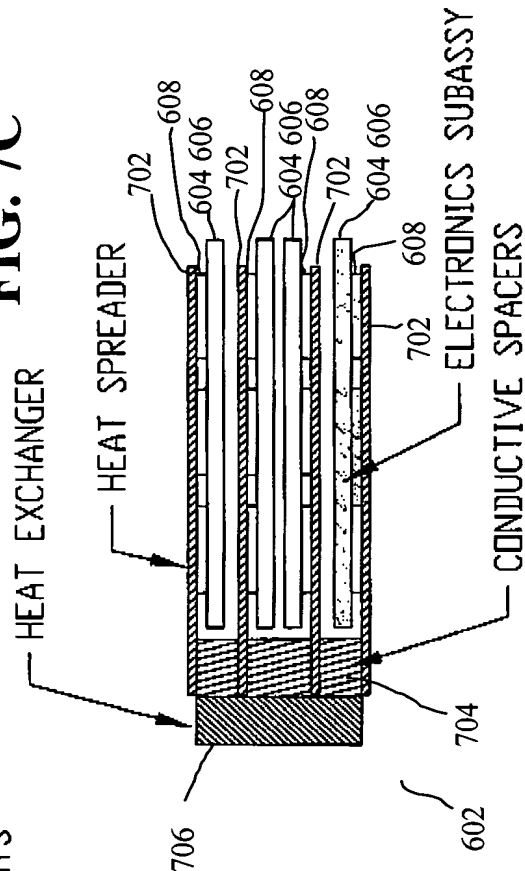


FIG. 7D

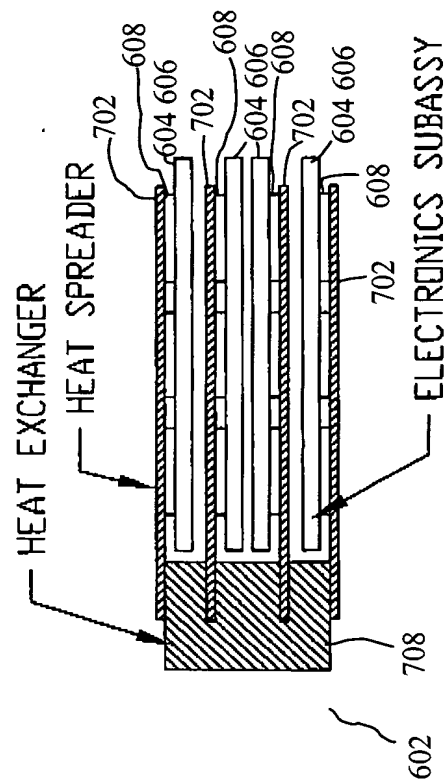
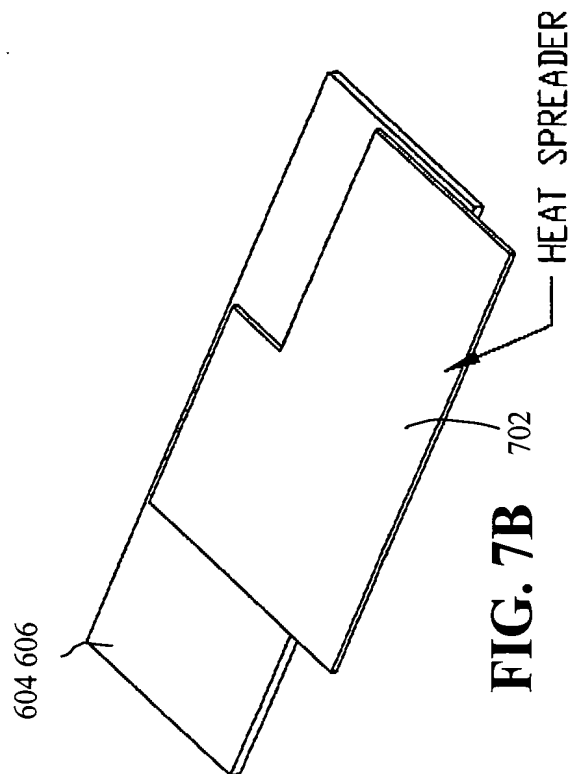


FIG. 7B



ELECTRONICS SUBASSY ON  
THERMALLY ENHANCED PC BOARD

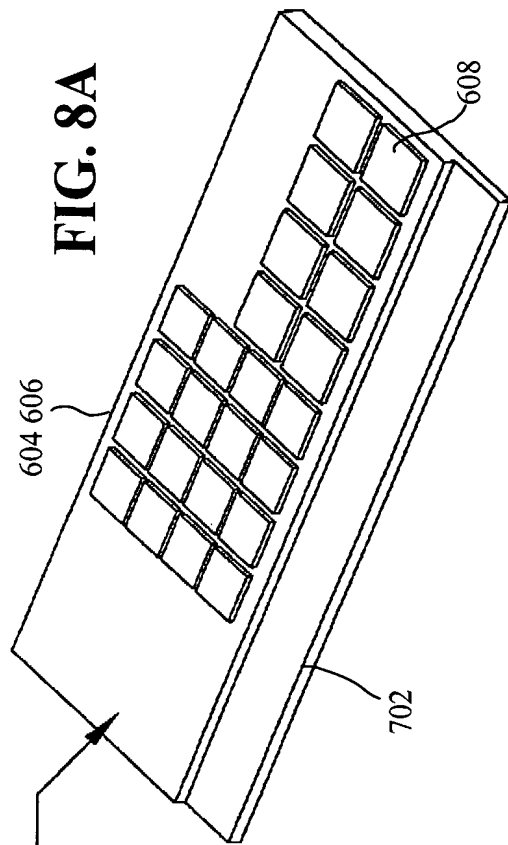


FIG. 8A

(7/11)

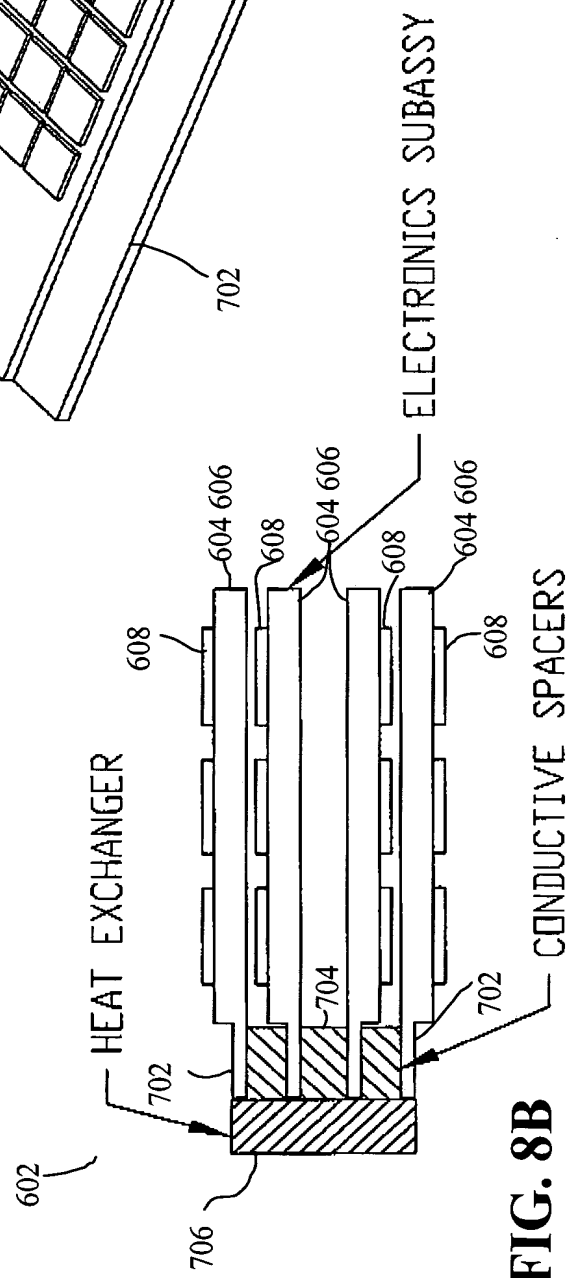


FIG. 8B

ELECTRONICS SUBASSY

HEAT PIPE

602

806

HEAT EXCHANGER

804

604 606

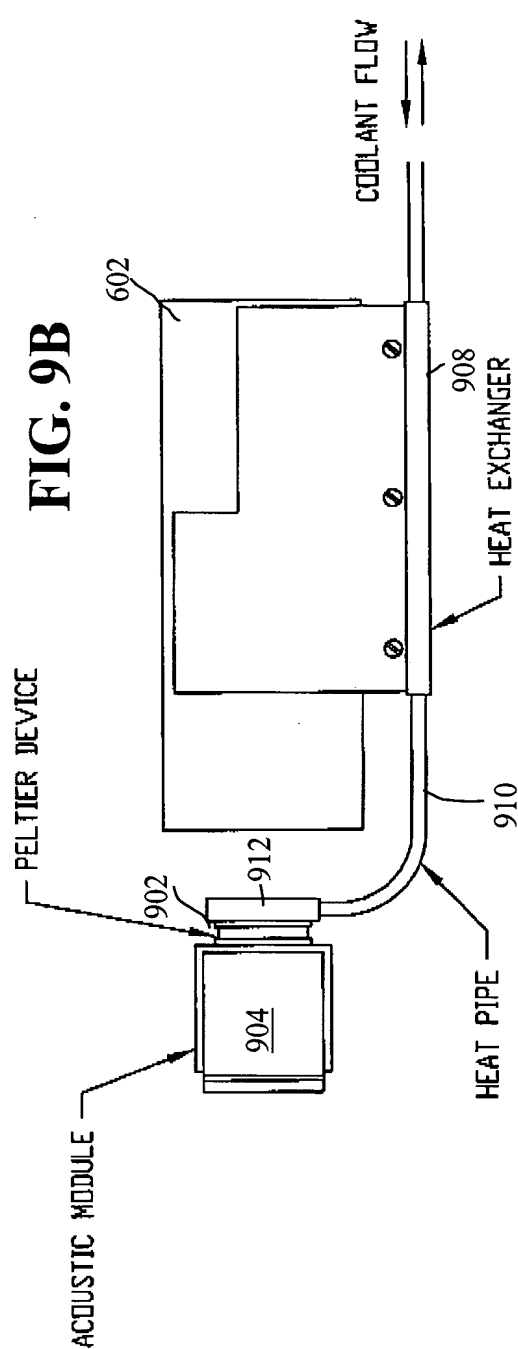
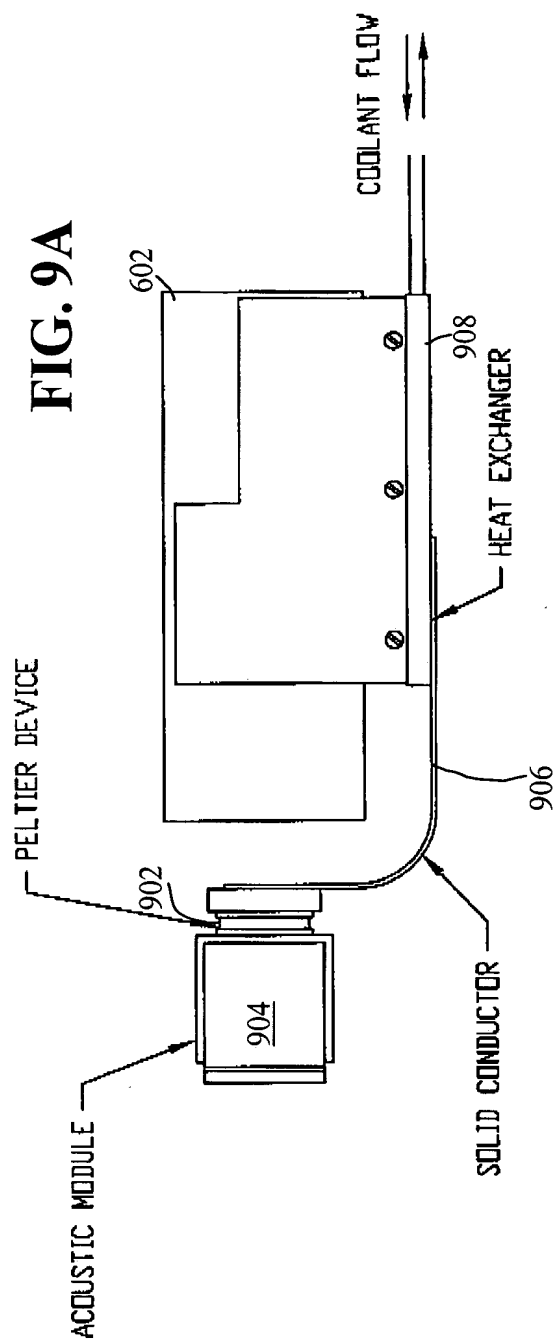
FIG. 8C

604 606

608

608

608



**FIG. 9**

(8/11)



